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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	18MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LED, POR, PWM, WDT
Number of I/O	26
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 3.6V
Data Converters	A/D 4x8b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	28-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p89lpc934fdh-529

3. Product comparison overview

Table 1 highlights the differences between the four devices. For a complete list of device features please see Section 2 “Features and benefits”.

Table 1. Product comparison overview

Device	Flash memory	Sector size	ADC1	ADC0	CCU	Data EEPROM
P89LPC933	4 kB	1 kB	X	-	-	-
P89LPC934	8 kB	1 kB	X	-	-	-
P89LPC935	8 kB	1 kB	X	X	X	X
P89LPC936	16 kB	2 kB	X	X	X	X

4. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
P89LPC935FA	PLCC28	plastic leaded chip carrier; 28 leads	SOT261-2
P89LPC933HDH	TSSOP28	plastic thin shrink small outline package; 28 leads; body width 4.4 mm	SOT361-1
P89LPC933FDH			
P89LPC934FDH			
P89LPC935FDH			
P89LPC936FDH			
P89LPC935FHN	HVQFN28	plastic thermal enhanced very thin quad flat package; no leads; 28 terminals; body 6 × 6 × 0.85 mm	SOT788-1

4.1 Ordering options

Table 3. Ordering options

Type number	Flash memory	Temperature range	Frequency
P89LPC933HDH	4 kB	−40 °C to +125 °C	0 MHz to 18 MHz
P89LPC933FDH	4 kB	−40 °C to +85 °C	
P89LPC935FA	8 kB		
P89LPC934FDH			
P89LPC935FDH			
P89LPC935FHN			
P89LPC936FDH	16 kB		

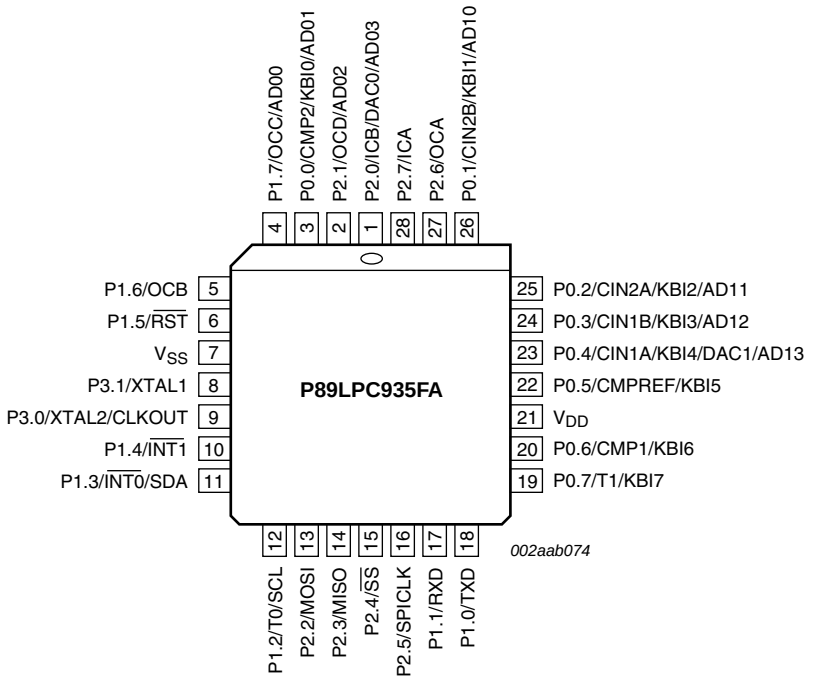

Fig 4. P89LPC935 PLCC28 pin configuration

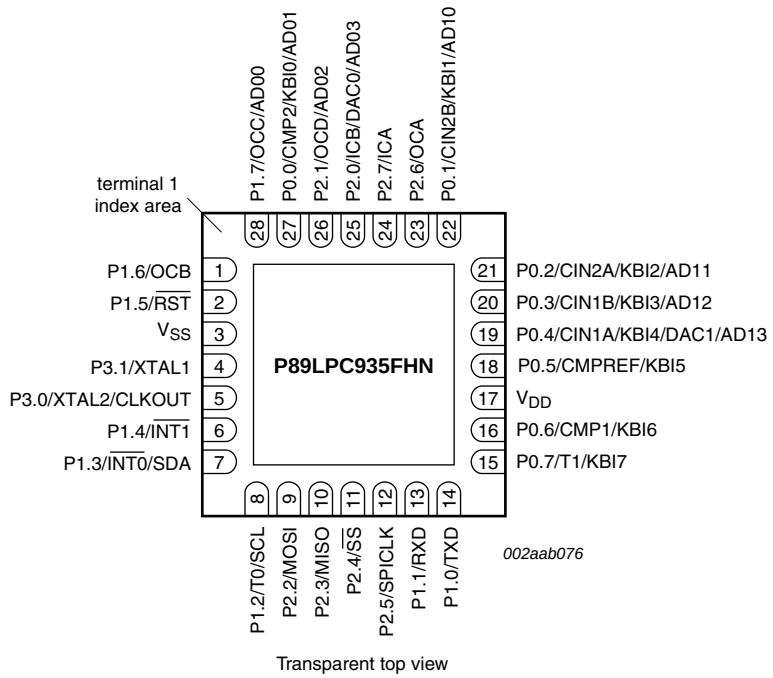

Fig 5. P89LPC935 HVQFN28 pin configuration

Table 5. Special function registers - P89LPC933/934

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
	Bit address		**E7**	**E6**	**E5**	**E4**	**E3**	**E2**	**E1**	**E0**		
ACC*	Accumulator	E0H									00	0000 0000
ADCON0	A/D control register 0	8EH	-	-	-	-	-	ENADC0	-	-	00	0000 0000
ADCON1	A/D control register 1	97H	ENBI1	ENADCI 1	TMM1	EDGE1	ADCI1	ENADC1	ADCS11	ADCS10	00	0000 0000
ADINS	A/D input select	A3H	ADI13	ADI12	ADI11	ADI10	-	-	-	-	00	0000 0000
ADMODA	A/D mode register A	C0H	BNDI1	BURST1	SCC1	SCAN1	-	-	-	-	00	0000 0000
ADMODB	A/D mode register B	A1H	CLK2	CLK1	CLK0	-	ENDAC1	ENDAC0	BSA1	-	00	000x 0000
AD0DAT3	A/D_0 data register 3	F4H									00	0000 0000
AD1BH	A/D_1 boundary high register	C4H									FF	1111 1111
AD1BL	A/D_1 boundary low register	BCH									00	0000 0000
AD1DAT0	A/D_1 data register 0	D5H									00	0000 0000
AD1DAT1	A/D_1 data register 1	D6H									00	0000 0000
AD1DAT2	A/D_1 data register 2	D7H									00	0000 0000
AD1DAT3	A/D_1 data register 3	F5H									00	0000 0000
AUXR1	Auxiliary function register	A2H	CLKLP	EBRR	ENT1	ENT0	SRST	0	-	DPS	00[1]	0000 00x0
	Bit address		**F7**	**F6**	**F5**	**F4**	**F3**	**F2**	**F1**	**F0**		
B*	B register	F0H									00	0000 0000
BRGR0	Baud rate generator rate low	BEH									00[2]	0000 0000
BRGR1	Baud rate generator rate high	BFH									00[1][2]	0000 0000
BRGCON	Baud rate generator control	BDH	-	-	-	-	-	-	SBRGS	BRGEN	00[2]	xxxx xx00
CMP1	Comparator 1 control register	ACH	-	-	CE1	CP1	CN1	OE1	CO1	CMF1	00[1]	xx00 0000
CMP2	Comparator 2 control register	ADH	-	-	CE2	CP2	CN2	OE2	CO2	CMF2	00[1]	xx00 0000
DIVM	CPU clock divide-by-M control	95H									00	0000 0000
DPTR	Data pointer (2 bytes)											
DPH	Data pointer high	83H									00	0000 0000
DPL	Data pointer low	82H									00	0000 0000
FMADRH	Program flash address high	E7H									00	0000 0000

Table 5. Special function registers - P89LPC933/934 *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
RTCH	Real-time clock register high	D2H									00[5]	0000 0000
RTCL	Real-time clock register low	D3H									00[5]	0000 0000
SADDR	Serial port address register	A9H									00	0000 0000
SADEN	Serial port address enable	B9H									00	0000 0000
SBUF	Serial Port data buffer register	99H									xx	xxxx xxxx
	Bit address		**9F**	**9E**	**9D**	**9C**	**9B**	**9A**	**99**	**98**		
SCON*	Serial port control	98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00	0000 0000
SSTAT	Serial port extended status register	BAH	DBMOD	INTLO	CIDIS	DBISEL	FE	BR	OE	STINT	00	0000 0000
SP	Stack pointer	81H									07	0000 0111
SPCTL	SPI control register	E2H	SSIG	SPEN	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	04	0000 0100
SPSTAT	SPI status register	E1H	SPIF	WCOL	-	-	-	-	-	-	00	00xx xxxx
SPDAT	SPI data register	E3H									00	0000 0000
TAMOD	Timer 0 and 1 auxiliary mode	8FH	-	-	-	T1M2	-	-	-	T0M2	00	xxx0 xxx0
	Bit address		**8F**	**8E**	**8D**	**8C**	**8B**	**8A**	**89**	**88**		
TCON*	Timer 0 and 1 control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00	0000 0000
TH0	Timer 0 high	8CH									00	0000 0000
TH1	Timer 1 high	8DH									00	0000 0000
TL0	Timer 0 low	8AH									00	0000 0000
TL1	Timer 1 low	8BH									00	0000 0000
TMOD	Timer 0 and 1 mode	89H	T1GATE	T1C/T	T1M1	T1M0	T0GATE	T0C/T	T0M1	T0M0	00	0000 0000
TRIM	Internal oscillator trim register	96H	RCCLK	ENCLK	TRIM.5	TRIM.4	TRIM.3	TRIM.2	TRIM.1	TRIM.0		[6] [5]
WDCON	Watchdog control register	A7H	PRE2	PRE1	PRE0	-	-	WDRUN	WDTOF	WDCLK		[7] [5]

Table 6. Special function registers - P89LPC935/936 *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
CCCRB	Capture compare B control register	EBH	ICECB2	ICECB1	ICECB0	ICESB	ICNFB	FCOB	OCMB1	OCMB0	00	0000 0000
CCCRC	Capture compare C control register	ECH	-	-	-	-	-	FCOC	OCMC1	OCMC0	00	xxxx x000
CCCRD	Capture compare D control register	EDH	-	-	-	-	-	FCOD	OCMD1	OCMD0	00	xxxx x000
CMP1	Comparator 1 control register	ACH	-	-	CE1	CP1	CN1	OE1	CO1	CMF1	00[3]	xx00 0000
CMP2	Comparator 2 control register	ADH	-	-	CE2	CP2	CN2	OE2	CO2	CMF2	00[3]	xx00 0000
DEECON	Data EEPROM control register	F1H	EEIF	HVERR	ECTL1	ECTL0	-	-	-	EADR8	0E	0000 1110
DEEDAT	Data EEPROM data register	F2H									00	0000 0000
DEEADR	Data EEPROM address register	F3H									00	0000 0000
DIVM	CPU clock divide-by-M control	95H									00	0000 0000
DPTR	Data pointer (2 bytes)											
DPH	Data pointer high	83H									00	0000 0000
DPL	Data pointer low	82H									00	0000 0000
FMADRH	Program flash address high	E7H									00	0000 0000
FMADRL	Program flash address low	E6H									00	0000 0000
FMCON	Program flash control (Read)	E4H	BUSY	-	-	-	HVA	HVE	SV	OI	70	0111 0000
	Program flash control (Write)	E4H	FMCMD.7	FMCMD.6	FMCMD.5	FMCMD.4	FMCMD.3	FMCMD.2	FMCMD.1	FMCMD.0		
FMDATA	Program flash data	E5H									00	0000 0000
I2ADR	I^2C slave address register	DBH	I2ADR.6	I2ADR.5	I2ADR.4	I2ADR.3	I2ADR.2	I2ADR.1	I2ADR.0	GC	00	0000 0000
	Bit address		**DF**	**DE**	**DD**	**DC**	**DB**	**DA**	**D9**	**D8**		
I2CON*	I^2C control register	D8H	-	I2EN	STA	STO	SI	AA	-	CRSEL	00	x000 00x0
I2DAT	I^2C data register	DAH										
I2SCLH	Serial clock generator/SCL duty cycle register high	DDH									00	0000 0000

external clock input on X1) and if the RTC is not using the crystal oscillator as its clock source. This allows external devices to synchronize to the P89LPC933/934/935/936. This output is enabled by the ENCLK bit in the TRIM register.

The frequency of this clock output is $\frac{1}{2}$ that of the CCLK. If the clock output is not needed in Idle mode, it may be turned off prior to entering Idle, saving additional power.

8.4 On-chip RC oscillator option

The P89LPC933/934/935/936 has a 6-bit TRIM register that can be used to tune the frequency of the RC oscillator. During reset, the TRIM value is initialized to a factory preprogrammed value to adjust the oscillator frequency to 7.373 MHz $\pm$ 1 % at room temperature. End-user applications can write to the TRIM register to adjust the on-chip RC oscillator to other frequencies.

8.5 Watchdog oscillator option

The watchdog has a separate oscillator which has a frequency of 400 kHz. This oscillator can be used to save power when a high clock frequency is not needed.

8.6 External clock input option

In this configuration, the processor clock is derived from an external source driving the P3.1/XTAL1 pin. The rate may be from 0 Hz up to 18 MHz. The P3.0/XTAL2 pin may be used as a standard port pin or a clock output. **When using an oscillator frequency above 12 MHz, the reset input function of P1.5 must be enabled. An external circuit is required to hold the device in reset at power-up until VDD has reached its specified level. When system power is removed VDD will fall below the minimum specified operating voltage. When using an oscillator frequency above 12 MHz, in some applications, an external brownout detect circuit may be required to hold the device in reset when VDD falls below the minimum specified operating voltage.**

8.7 CCLK wake-up delay

The P89LPC933/934/935/936 has an internal wake-up timer that delays the clock until it stabilizes depending on the clock source used. If the clock source is any of the three crystal selections (low, medium and high frequencies) the delay is 992 OSCCLK cycles plus 60 μs to 100 μs. If the clock source is either the internal RC oscillator, watchdog oscillator, or external clock, the delay is 224 OSCCLK cycles plus 60 μs to 100 μs.

8.8 CCLK modification: DIVM register

The OSCCLK frequency can be divided down up to 510 times by configuring a dividing register, DIVM, to generate CCLK. This feature makes it possible to temporarily run the CPU at a lower rate, reducing power consumption. By dividing the clock, the CPU can retain the ability to respond to events that would not exit Idle mode by executing its normal program at a lower rate. This can also allow bypassing the oscillator start-up time in cases where Power-down mode would otherwise be used. The value of DIVM may be changed by the program at any time without interrupting code execution.

8.9 Low power select

The P89LPC933/934/935/936 is designed to run at 18 MHz (CCLK) maximum. However, if CCLK is 8 MHz or slower, the CLKLP SFR bit (AUXR1.7) can be set to logic 1 to lower the power consumption further. On any reset, CLKLP is logic 0 allowing highest performance access. This bit can then be set in software if CCLK is running at 8 MHz or slower.

8.10 Memory organization

The various P89LPC933/934/935/936 memory spaces are as follows:

- DATA

  128 bytes of internal data memory space (00H:7FH) accessed via direct or indirect addressing, using instructions other than MOVX and MOVC. All or part of the Stack may be in this area.

- IDATA

  Indirect Data. 256 bytes of internal data memory space (00H:FFH) accessed via indirect addressing using instructions other than MOVX and MOVC. All or part of the Stack may be in this area. This area includes the DATA area and the 128 bytes immediately above it.

- SFR

  Selected CPU registers and peripheral control and status registers, accessible only via direct addressing.

- XDATA (P89LPC935/936)

  ‘External’ Data or Auxiliary RAM. Duplicates the classic 80C51 64 kB memory space addressed via the MOVX instruction using the SPTR, R0, or R1. All or part of this space could be implemented on-chip. The P89LPC935/936 has 512 bytes of on-chip XDATA memory.

not being used as the CPU clock. If the XTAL oscillator is used as the CPU clock, then the RTC will use CCLK as its clock source. Only power-on reset will reset the RTC and its associated SFRs to the default state.

8.19 CCU (P89LPC935/936)

This unit features:

- A 16-bit timer with 16-bit reload on overflow.
- Selectable clock, with prescaler to divide clock source by any integral number between 1 and 1024.
- Four compare/PWM outputs with selectable polarity.
- Symmetrical/asymmetrical PWM selection.
- Two capture inputs with event counter and digital noise rejection filter.
- Seven interrupts with common interrupt vector (one overflow, two capture, four compare).
- Safe 16-bit read/write via shadow registers.

8.19.1 CCU clock

The CCU runs on the CCUCLK, which is either PCLK in basic timer mode, or the output of a Phase-Locked Loop (PLL). The PLL is designed to use a clock source between 0.5 MHz to 1 MHz that is multiplied by 32 to produce a CCUCLK between 16 MHz and 32 MHz in PWM mode (asymmetrical or symmetrical). The PLL contains a 4-bit divider to help divide PCLK into a frequency between 0.5 MHz and 1 MHz.

8.19.2 CCUCLK prescaling

This CCUCLK can further be divided down by a prescaler. The prescaler is implemented as a 10-bit free-running counter with programmable reload at overflow.

8.19.3 Basic timer operation

The timer is a free-running up/down counter with a direction control bit. If the timer counting direction is changed while the counter is running, the count sequence will be reversed. The timer can be written or read at any time.

When a reload occurs, the CCU Timer Overflow Interrupt Flag will be set, and an interrupt generated if enabled. The 16-bit CCU timer may also be used as an 8-bit up/down timer.

8.19.4 Output compare

There are four output compare channels A, B, C and D. Each output compare channel needs to be enabled in order to operate and the user will have to set the associated I/O pin to the desired output mode to connect the pin. When the contents of the timer matches that of a capture compare control register, the Timer Output Compare Interrupt Flag (TOCFx) becomes set. An interrupt will occur if enabled.

8.19.5 Input capture

Input capture is always enabled. Each time a capture event occurs on one of the two input capture pins, the contents of the timer is transferred to the corresponding 16-bit input capture register. The capture event can be programmed to be either rising or falling edge triggered. A simple noise filter can be enabled on the input capture by enabling the Input

8.19.7 Alternating output mode

In asymmetrical mode, the user can set up PWM channels A/B and C/D as alternating pairs for bridge drive control. In this mode the output of these PWM channels are alternately gated on every counter cycle.

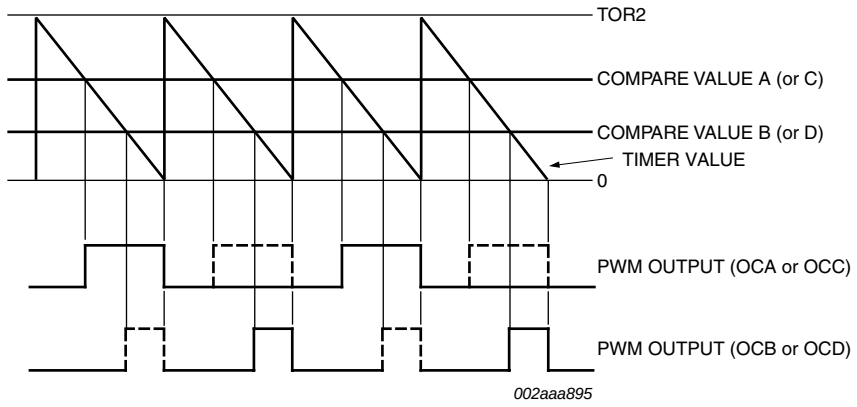

Fig 12. Alternate output mode

8.19.8 PLL operation

The PWM module features a PLL that can be used to generate a CCUCLK frequency between 16 MHz and 32 MHz. At this frequency the PWM module provides ultrasonic PWM frequency with 10-bit resolution provided that the crystal frequency is 1 MHz or higher. The PLL is fed an input signal from 0.5 MHz to 1 MHz and generates an output signal of 32 times the input frequency. This signal is used to clock the timer. The user will have to set a divider that scales PCLK by a factor from 1 to 16. This divider is found in the SFR register TCR21. The PLL frequency can be expressed as shown in Equation 1.

$$\text{PLL frequency} = \frac{\text{PCLK}}{(N+1)} \quad (1)$$

Where: N is the value of PLLDV.3 to PLLDV.0.

Since N ranges from 0 to 15, the CCLK frequency can be in the range of PCLK to $^{PCLK}/_{16}$.

8.22 SPI

The P89LPC933/934/935/936 provides another high-speed serial communication interface—the SPI interface. SPI is a full-duplex, high-speed, synchronous communication bus with two operation modes: Master mode and Slave mode. Up to 3 Mbit/s can be supported in Master mode or up to 2 Mbit/s in Slave mode. It has a Transfer Completion Flag and Write Collision Flag Protection.

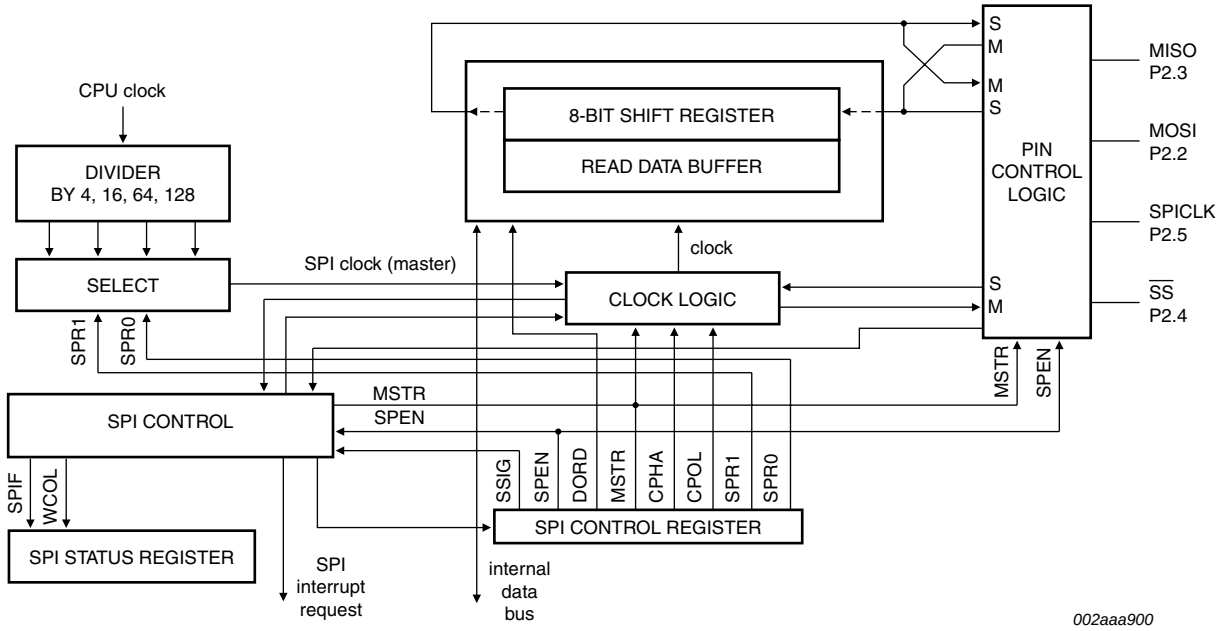

Fig 17. SPI block diagram

The SPI interface has four pins: SPICLK, MOSI, MISO and $\overline{SS}$:

- SPICLK, MOSI and MISO are typically tied together between two or more SPI devices. Data flows from master to slave on MOSI (Master Out Slave In) pin and flows from slave to master on MISO (Master In Slave Out) pin. The SPICLK signal is output in the master mode and is input in the slave mode. If the SPI system is disabled, i.e., SPEN (SPCTL.6) = 0 (reset value), these pins are configured for port functions.
- $\overline{SS}$ is the optional slave select pin. In a typical configuration, an SPI master asserts one of its port pins to select one SPI device as the current slave. An SPI slave device uses its $\overline{SS}$ pin to determine whether it is selected.

Typical connections are shown in Figure 18 through Figure 20.

8.23 Analog comparators

Two analog comparators are provided on the P89LPC933/934/935/936. Input and output options allow use of the comparators in a number of different configurations. Comparator operation is such that the output is a logic 1 (which may be read in a register and/or routed to a pin) when the positive input (one of two selectable pins) is greater than the negative input (selectable from a pin or an internal reference voltage). Otherwise the output is a zero. Each comparator may be configured to cause an interrupt when the output value changes.

The overall connections to both comparators are shown in Figure 21. The comparators function to V_{DD} = 2.4 V.

When each comparator is first enabled, the comparator output and interrupt flag are not guaranteed to be stable for 10 microseconds. The corresponding comparator interrupt should not be enabled during that time, and the comparator interrupt flag must be cleared before the interrupt is enabled in order to prevent an immediate interrupt service.

When a comparator is disabled the comparator's output, COn, goes HIGH. If the comparator output was LOW and then is disabled, the resulting transition of the comparator output from a LOW to HIGH state will set the comparator flag, CMFn. This will cause an interrupt if the comparator interrupt is enabled. The user should therefore disable the comparator interrupt prior to disabling the comparator. Additionally, the user should clear the comparator flag, CMFn, after disabling the comparator.

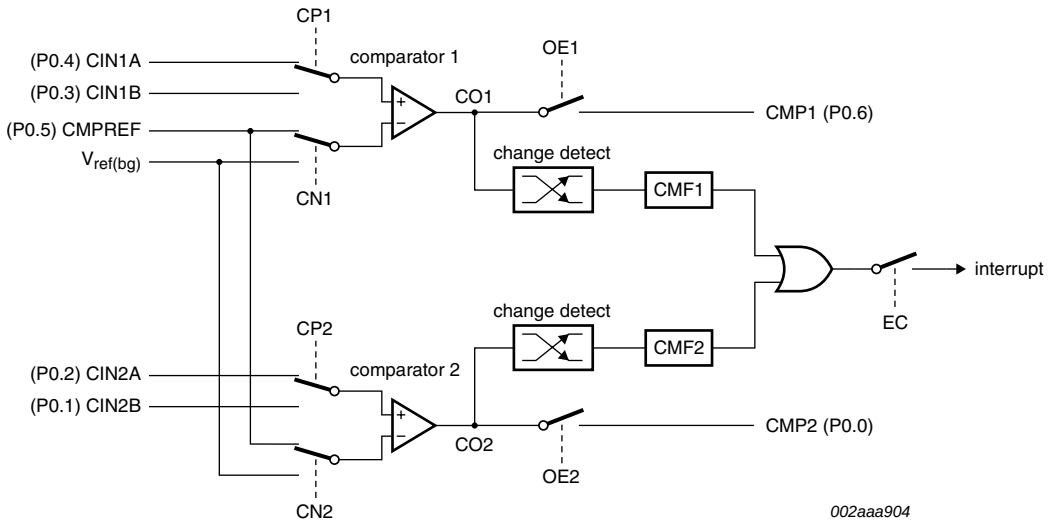

Fig 21. Comparator input and output connections

8.23.1 Internal reference voltage

An internal reference voltage generator may supply a default reference when a single comparator input pin is used. The value of the internal reference voltage, referred to as $V_{ref(bg)}$, is 1.23 V ± 10 %.

8.23.2 Comparator interrupt

Each comparator has an interrupt flag contained in its configuration register. This flag is set whenever the comparator output changes state. The flag may be polled by software or may be used to generate an interrupt. The two comparators use one common interrupt vector. If both comparators enable interrupts, after entering the interrupt service routine, the user needs to read the flags to determine which comparator caused the interrupt.

8.23.3 Comparators and power reduction modes

Either or both comparators may remain enabled when Power-down or Idle mode is activated, but both comparators are disabled automatically in Total Power-down mode.

If a comparator interrupt is enabled (except in Total Power-down mode), a change of the comparator output state will generate an interrupt and wake-up the processor. If the comparator output to a pin is enabled, the pin should be configured in the push-pull mode in order to obtain fast switching times while in Power-down mode. The reason is that with the **oscillator** stopped, the temporary strong pull-up that normally occurs during switching on a quasi-bidirectional port pin does not take place.

Comparators consume power in Power-down and Idle modes, as well as in the normal operating mode. This fact should be taken into account when system power consumption is an issue. To minimize power consumption, the user can disable the comparators via PCONA.5, or put the device in Total Power-down mode.

8.24 Keypad interrupt

The Keypad Interrupt (KBI) function is intended primarily to allow a single interrupt to be generated when Port 0 is equal to or not equal to a certain pattern. This function can be used for bus address recognition or keypad recognition. The user can configure the port via SFRs for different tasks.

The Keypad Interrupt Mask register (KBMASK) is used to define which input pins connected to Port 0 can trigger the interrupt. The Keypad Pattern register (KBPATN) is used to define a pattern that is compared to the value of Port 0. The Keypad Interrupt Flag (KBIF) in the Keypad Interrupt Control register (KBCON) is set when the condition is matched while the Keypad Interrupt function is active. An interrupt will be generated if enabled. The PATN_SEL bit in the Keypad Interrupt Control register (KBCON) is used to define equal or not-equal for the comparison.

In order to use the Keypad Interrupt as an original KBI function like in 87LPC76x series, the user needs to set KBPATN = 0FFH and PATN_SEL = 1 (not equal), then any key connected to Port 0 which is enabled by the KBMASK register will cause the hardware to set KBIF and generate an interrupt if it has been enabled. The interrupt may be used to wake-up the CPU from Idle or Power-down modes. This feature is particularly useful in handheld, battery-powered systems that need to carefully manage power consumption yet also need to be convenient to use.

In order to set the flag and cause an interrupt, the pattern on Port 0 must be held longer than six CCLKs.

- ◆ Start immediately.
- ◆ Edge triggered.
- ◆ Dual start immediately (P89LPC935/936).

- 8-bit conversion time of ≥3.9 μs at an A/D clock of 3.3 MHz.
- Interrupt or polled operation.
- Boundary limits interrupt.
- DAC output to a port pin with high output impedance.
- Clock divider.
- Power-down mode.

9.3 Block diagram

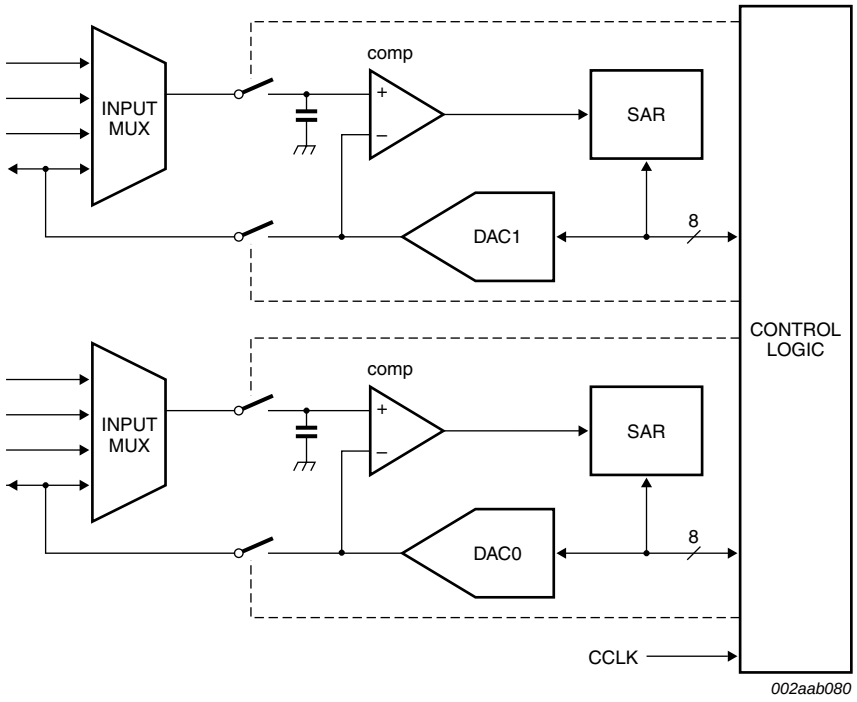

Fig 23. ADC block diagram

9.4 A/D operating modes

9.4.1 Fixed channel, single conversion mode

A single input channel can be selected for conversion. A single conversion will be performed and the result placed in the result register which corresponds to the selected input channel. An interrupt, if enabled, will be generated after the conversion completes.

10. Limiting values

Table 10. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).[1]

Symbol	Parameter	Conditions	Min	Max	Unit
$T_{amb(bias)}$	bias ambient temperature		−55	+125	°C
T_{stg}	storage temperature		−65	+150	°C
$I_{OH(I/O)}$	HIGH-level output current per input/output pin		-	20	mA
$I_{OL(I/O)}$	LOW-level output current per input/output pin		-	20	mA
$I_{I/Otot(max)}$	maximum total input/output current		-	100	mA
V_{xtal}	crystal voltage	on XTAL1, XTAL2 pin to V_{SS}	-	V_{DD} + 0.5	V
V_n	voltage on any other pin	except XTAL1, XTAL2 to V_{SS}	−0.5	+5.5	V
$P_{tot(pack)}$	total power dissipation (per package)	based on package heat transfer, not device power consumption	-	1.5	W

[1] The following applies to Table 10:

a) This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

b) Parameters are valid over ambient temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

11. Static characteristics

Table 11. Static characteristics

V_{DD} = 2.4 V to 3.6 V unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial, −40 °C to +125 °C for extended, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
$I_{DD(oper)}$	operating supply current	V_{DD} = 3.6 V; f_{osc} = 12 MHz	[2]	-	11	18	mA
		V_{DD} = 3.6 V; f_{osc} = 18 MHz	[2]	-	14	23	mA
$I_{DD(idle)}$	Idle mode supply current	V_{DD} = 3.6 V; f_{osc} = 12 MHz	[2]	-	3.25	5	mA
		V_{DD} = 3.6 V; f_{osc} = 18 MHz	[2]	-	5	7	mA
$I_{DD(pd)}$	Power-down mode supply current	V_{DD} = 3.6 V; voltage comparators powered down	[2]	-	55	80	μA
$I_{DD(tpd)}$	total Power-down mode supply current	all devices except P89LPC933HDH; V_{DD} = 3.6 V	[3]	-	1	5	μA
		P89LPC933HDH only; V_{DD} = 3.6 V	[3]	-	-	25	μA
$(dV/dt)_r$	rise rate	of V_{DD}		-	-	2	mV/μs
$(dV/dt)_f$	fall rate	of V_{DD}		-	-	50	mV/μs
V_{POR}	power-on reset voltage			-	-	0.5	V
V_{DDR}	data retention supply voltage			1.5	-	-	V
$V_{th(HL)}$	HIGH-LOW threshold voltage	except SCL, SDA		$0.22V_{DD}$	$0.4V_{DD}$	-	V
V_{IL}	LOW-level input voltage	SCL, SDA only		−0.5	-	$0.3V_{DD}$	V
$V_{th(LH)}$	LOW-HIGH threshold voltage	except SCL, SDA		-	$0.6V_{DD}$	$0.7V_{DD}$	V
V_{IH}	HIGH-level input voltage	SCL, SDA only		$0.7V_{DD}$	-	5.5	V
V_{hys}	hysteresis voltage	port 1		-	$0.2V_{DD}$	-	V
V_{OL}	LOW-level output voltage	I_{OL} = 20 mA; V_{DD} = 2.4 V to 3.6 V all ports, all modes except high-Z	[4]	-	0.6	1.0	V
		I_{OL} = 3.2 mA; V_{DD} = 2.4 V to 3.6 V all ports, all modes except high-Z		-	0.2	0.3	V
V_{OH}	HIGH-level output voltage	I_{OH} = −20 μA; V_{DD} = 2.4 V to 3.6 V; all ports, quasi-bidirectional mode		V_{DD} − 0.3	V_{DD} − 0.2	-	V
		I_{OH} = −3.2 mA; V_{DD} = 2.4 V to 3.6 V; all ports, push-pull mode		V_{DD} − 0.7	V_{DD} − 0.4	-	V
		I_{OH} = −10 mA; V_{DD} = 3.6 V; all ports, push-pull mode		-	3.2	-	V
V_{xtal}	crystal voltage	on XTAL1, XTAL2 pins; with respect to V_{SS}		−0.5	-	+4.0	V
V_n	voltage on any other pin	except XTAL1, XTAL2, V_{DD}; with respect to V_{SS}	[5]	−0.5	-	+5.5	V
C_{iss}	input capacitance		[6]	-	-	15	pF

Table 11. Static characteristics *…continued*

V_{DD} = 2.4 V to 3.6 V unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial, −40 °C to +125 °C for extended, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I_{IL}	LOW-level input current	V_I = 0.4 V	[7]	-	-	−80	μA
I_{LI}	input leakage current	$V_I = V_{IL}$, V_{IH} or $V_{th(HL)}$	[8]	-	-	±10	μA
I_{THL}	HIGH-LOW transition current	all ports; V_I = 1.5 V at V_{DD} = 3.6 V	[9]	−30	-	−450	μA
$R_{RST\_N(int)}$	internal pull-up resistance on pin $\overline{RST}$			10	-	30	kΩ
V_{bo}	brownout trip voltage	2.4 V < V_{DD} < 3.6 V; with BOV = 1, BOPD = 0		2.40	-	2.70	V
$V_{ref(bg)}$	band gap reference voltage			1.11	1.23	1.34	V
TC_{bg}	band gap temperature coefficient			-	10	20	ppm/°C

[1] Typical ratings are not guaranteed. The values listed are at room temperature, 3 V.

[2] The $I_{DD(oper)}$, $I_{DD(idle)}$, and $I_{DD(pd)}$ specifications are measured using an external clock with the following functions disabled: comparators, real-time clock, and watchdog timer.

[3] The $I_{DD(tpd)}$ specification is measured using an external clock with the following functions disabled: comparators, real-time clock, brownout detect, and watchdog timer.

[4] See Section 10 “Limiting values” for steady state (non-transient) limits on I_{OL} or I_{OH}. If I_{OL}/I_{OH} exceeds the test condition, V_{OL}/V_{OH} may exceed the related specification.

[5] This specification can be applied to pins which have A/D input or analog comparator input functions when the pin is not being used for those analog functions. When the pin is being used as an analog input pin, the maximum voltage on the pin must be limited to 4.0 V with respect to V_{SS}.

[6] Pin capacitance is characterized but not tested.

[7] Measured with port in quasi-bidirectional mode.

[8] Measured with port in high-impedance mode.

[9] Port pins source a transition current when used in quasi-bidirectional mode and externally driven from logic 1 to logic 0. This current is highest when V_I is approximately 2 V.

Table 12. Dynamic characteristics (12 MHz) *…continued*

V_{DD} = 2.4 V to 3.6 V unless otherwise specified.

T_{amb} = −40 °C to +85 °C for industrial, −40 °C to +125 °C for extended, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 12 MHz		Unit
			Min	Max	Min	Max	
t_{SPILAG}	SPI enable lag time	see Figure 29, 30					
	slave		250	-	250	-	ns
$t_{SPICLKH}$	SPICLK HIGH time	see Figure 26, 28, 29, 30					
	master		$^{2}/_{CCLK}$	-	165	-	ns
	slave		$^{3}/_{CCLK}$	-	250	-	ns
$t_{SPICLKL}$	SPICLK LOW time	see Figure 26, 28, 29, 30					
	master		$^{2}/_{CCLK}$	-	165	-	ns
	slave		$^{3}/_{CCLK}$	-	250	-	ns
t_{SPIDSU}	SPI data set-up time	see Figure 26, 28, 29, 30					
	master or slave		100	-	100	-	ns
t_{SPIDH}	SPI data hold time	see Figure 26, 28, 29, 30					
	master or slave		100	-	100	-	ns
t_{SPIA}	SPI access time	see Figure 29, 30					
	slave		0	120	0	120	ns
t_{SPIDIS}	SPI disable time	see Figure 29, 30					
	slave		0	240	-	240	ns
t_{SPIDV}	SPI enable to output data valid time	see Figure 26, 28, 29, 30					
	slave		-	240	-	240	ns
	master		-	167	-	167	ns
t_{SPIOH}	SPI output data hold time	see Figure 26, 28, 29, 30	0	-	0	-	ns
t_{SPIR}	SPI rise time	see Figure 26, 28, 29, 30					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns
t_{SPIF}	SPI fall time	see Figure 26, 28, 29, 30					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns

[1] Parameters are valid over ambient temperature range unless otherwise specified.

[2] Parts are tested to 2 MHz, but are guaranteed to operate down to 0 Hz.

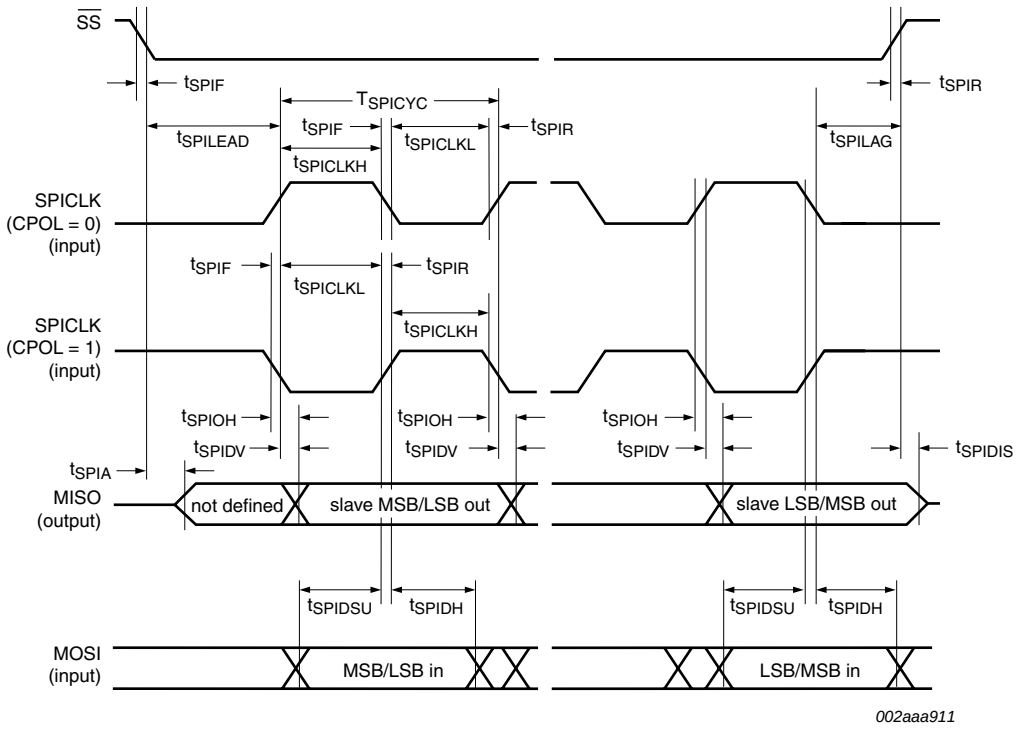

Fig 30. SPI slave timing (CPHA = 1)

12.2 ISP entry mode

Table 14. Dynamic characteristics, ISP entry mode

V_{DD} = 2.4 V to 3.6 V, unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial, −40 °C to +125 °C for extended, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_{VR}	$\overline{RST}$ delay from V_{DD} active time		50	-	-	µs
t_{RH}	$\overline{RST}$ HIGH time		1	-	32	µs
t_{RL}	$\overline{RST}$ LOW time		1	-	-	µs

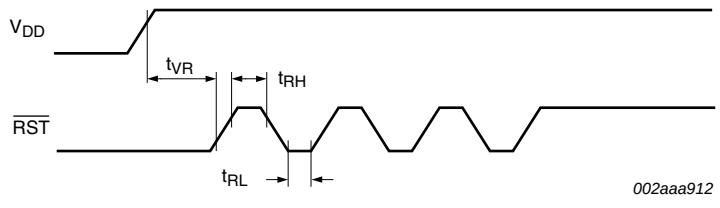

Fig 31. ISP entry timing

13. Other characteristics

13.1 Comparator electrical characteristics

Table 15. Comparator electrical characteristics

V_{DD} = 2.4 V to 3.6 V, unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial, −40 °C to +125 °C for extended, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IO}	input offset voltage		-	-	±20	mV
V_{IC}	common-mode input voltage		0	-	V_{DD} − 0.3	V
CMRR	common-mode rejection ratio	[1]	-	-	−50	dB
$t_{res(tot)}$	total response time		-	250	500	ns
$t_{(CE-OV)}$	chip enable to output valid time		-	-	10	μs
I_{LI}	input leakage current	$0 < V_I < V_{DD}$	-	-	±10	μA

[1] This parameter is characterized, but not tested in production.

17. Legal information

17.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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